AMENDMENTS IN A MARKED VERSION

1. (Once Amended) A method comprising:

placing incomplete chip package into a mold formed by a first portion and a second portion, the incomplete chip package comprising a chip and a substrate electrically coupled using a flip chip process, the chip having (i) a top surface facing the substrate, (ii) a bottom surface opposite the top surface, and (iii) one or more side surfaces between the top and bottom surfaces;

injecting a liquid resin into a runner section of the mold, the runner formed between the first portion and the second portion, and the resin encapsulating a significant portion of the one or more side surfaces, and filling a first gap between the top surface and the adjacent substrate; and

curing the resin.

2. (Once Amended) The method of claim 1, wherein the chip and substrate [were] are electrically coupled by a plurality of reflowed solder bumps.

20. (Once Amended) A method comprising:

placing an incomplete flip chip package into a bottom inner cavity of a bottom mold portion,

the incomplete flip chip package comprising a chip and a substrate, the chip having a top surface coupled by reflowed solder bumps to a upper surface of the substrate, the chip further comprising a bottom surface opposite the top surface and one or more side surfaces between the top and bottom surfaces;

mating an upper mold portion with the lower mold portion, the upper mold portion having an upper inner cavity, the upper and bottom inner cavities forming a mold inner cavity enclosing the incomplete flip chip package, and forming a runner between the upper and lower mold portions;

injecting a predetermined amount of a liquid resin into the mold inner cavity through the runner, the liquid resin encapsulating [the] substantially all of the one or more side surfaces and substantially all

of the upper surface, the liquid resin further filling a gap between the top surface of the chip and an adjacent portion of the upper surface, encapsulating the reflowed solder bumps;

curing the liquid resin by maintaining the mold at an elevated temperature for a predetermined period of time, the elevated temperature being equal to or greater than the cure temperature of the filled liquid resin for the predetermined period of time.

31. - 32. (New)